



Product Change Notification

Change Notification #: 118931-00
Change Title: Select Intel® Server Board S2600WFQR, PCN 118931-00, Product Material, Over Current Protection (OCP) Integrated Circuit (IC) second source
Date of Publication: March 03, 2022

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	March 24, 2022
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change(s) on the item(s) listed in the "Products Affected" table.

- Adding a second source for the Over Current Protection (OCP) Integrated Circuit (IC) on the Server Board. The new IC is identical in form factor and function to the previous one.
- As a result, we are adding as alternates the following PBA in the Server Boards:
M71674-951
M71674-961

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Server Board S2600WFQR, Single	S2600WFQR	986006	K40812-006	H87178-951 H87178-961	K40812-007	H87178-951 H87178-961 M71674-951 M71674-961

PCN Revision History:

Date of Revision: March 03, 2022	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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Europe Email: eccb@intel.com

Japan Email: jcb.ijkk@intel.com

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